

## *2<sup>nd</sup> International Eco-electronics Conference*

*Sponsored by*  
**Ministry of Information Industry of China**

*Co-sponsor by*  
**Tsinghua University**

**December 7-9<sup>th</sup>, 2006**  
**Beijing International Convention Center**



<http://www.eco-e.org/>

## **Conference Background**

*Recently, as an important trend in the field of electronic manufacturing, EcoDesign has been considered much more than an environmental concept, it has been developed quickly toward an big market and business chance, especially after the enactment of RoHS/WEEE law system in EU and Other countries. At the same time, so many related standards, product categories, technical level, testing methods arising from this field have not been uniformed globally. To provide a chance as for the discussion on how to construct a stable development future of eco-electronics, some EcoDesigners from different countries proposed this conference.*

*Ministry of Information Industry of China, as a sponsor, will publish the new progress of Chinese RoHS/WEEE system during the conference. We sincerely invite you to join and share new information with us. Some friendly open discussion related to technology, market, management and policy of eco-electronics were expected in the conference.*

## **Language**

English / Chinese (English was highly recommended)

## **Topics**

- Global strategy & policy on Eco-electronics Industry.  
Recent progress on the RoHS/WEEE system in different countries, including standards, product category, RoHS certification will be discussed. The strategy on the development of Eco-electronics business will be shared.
- Design & technology on lead-free & halogen-free system.  
Design, material, process, reliability & simulation on the lead-free & halogen-free system will be discussed.
- Standard, testing & equipment on green electronics for RoHS system  
Standards on material composition of electronic product, RoHS testing technique, RoHS certificate procedure, RoHS solution, and RoHS related equipment system will be discussed.
- Construction and management of the system of Eco-electronics supply chain  
It will be discussed about how to construct an effective new green supply chain, how to mark the product, how to manage the storage of product, component, process....
- Recycle, technology & management on E-waste  
Recycle system construction, 3R, global collaboration, and product disassemble technique will be discussed.
- Collaboration of industry, education and research on Eco-electronics  
To ensure sustainable development of eco-electronic activity, it was necessary to develop active collaboration of industry, education and research.

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**IEEE-CPMT Beijing Chapter**  
**Chinese Electronic Packaging Society**  
**School of Material Science, Tsinghua University**  
**Component Sub-society, Chinese Electronic Society**  
**The University of Tokyo Wuxi Representative Office**  
**China-Japan Science & Technology Exchange Society**  
**Japan EcoDesign Promotion Network**

*Organized by*  
**Division of Electronic Material & Packaging Technology, Tsinghua University**  
**Wuxi International EcoDesign and Microelectronic Packaging Research Institute**



## **Paper Submission**

We sincerely invite you to attend the conference, paper submission was greatly encouraged. The abstract of 200 words should include title, author, contact information, brief content of paper, etc. Anyone who plan to submit paper, please send abstract by email or fax to the following address:

E-mail	xuzhonghua@tsinghua.org.cn xu.zhong@su.t.u-tokyo.ac.jp temptm@mail.tsinghua.edu.cn
Fax	0510-85225248 010-62772724

## **Important date**

Deadline for abstract	October 30 <sup>th</sup>
Paper acceptance notification	November 5 <sup>th</sup>
Deadline for paper	November 20 <sup>th</sup>
In site registration	December 6-8th
Conference date	December 7-8 <sup>th</sup>
Industry tour	December 9 <sup>th</sup>

## **Registration fee** (Including lunch, dinner & proceedings)

Student	In-site registration, Dec.6-8	75US\$
Student	Advanced registration by Nov.25	60US\$
Speaker (Non-student)	In-site registration, Dec.6-8	150US\$
Speaker (Non-student)	Advanced registration by Nov.25	135US\$
Non-speaker (Non-student)	In-site registration, Dec.6-8	200US\$
Non-speaker (Non-student)	Advanced registration by Nov.25	185US\$

1. Registration fee of in-site registration will be paid at conference site on Dec.6-8 by cash.
2. Registration fee of advanced registration must be paid by Nov.25 by the way of remittance to the following bank account:

**Beneficiary's name:** International Ecodesign and Microelectronic Packaging Research Institute Limited

**Postal code:** 214028

**Unit address:** Room 301-304, Building A, No.21, Changjiang Road  
New District, Wuxi, Jiangsu Province P.R.China

**Bank name:** Wuxi New District, Jiangsu Province, Agriculture Bank of China

**Bank address:** No.58 Wang Zhuang Road, WND, Jiangsu, China

**SWIFT:** ABOCCNBJ100

**Account number:** 1408010500141

**Notice:** Registration form was encouraged to be sent to the Organizer Secretariat by November 25<sup>th</sup> by Fax or e-mail.

## Conference draft agenda (To be updated)

December 6-8 <sup>th</sup>	Registration-whole day	
December 7 <sup>th</sup>	Morning	Keynote speech
	Afternoon	Group discussion
	Night	Welcome banquet
December 8 <sup>th</sup>	Morning	Group discussion
	Afternoon	Group discussion
	Night	Dinner
December 9 <sup>th</sup>	Industry tour	

## Conference site

### Beijing International Convention Center

Beijing International Convention Center, connected with Beijing Continental Grand Hotel, covers a constructional area of 60, 000 m<sup>2</sup>. It is a venue for international and domestic meetings, exhibition, and large-scale activities. It also serves as an office building. It is equipped with intelligent building control system, Wide Band, simultaneous interpretation facilities, and digital control system for audio, video, and lighting. All services for leisure and business are available here.

<http://www.bicc.com.cn/guanyu/dili.htm>



## “Secretariat of 2<sup>nd</sup> Eco-Electronics Conference”

Tel: +86-510-8522-5248; +86-10-6277-2724; +81-3-5841-6494  
Fax: +86-510-8522-5248; +86-10-6277-2724; +81-3-5841-6495;

E-mail: [xu.zhong@su.t.u-tokyo.ac.jp](mailto:xu.zhong@su.t.u-tokyo.ac.jp)  
[temptm@mail.tsinghua.edu.cn](mailto:temptm@mail.tsinghua.edu.cn)  
[xuzhonghua@tsinghua.org.cn](mailto:xuzhonghua@tsinghua.org.cn)

<http://www.eco-e.org/>

## Registration

Unit name			
Unit address		P.C.	
Name	Title	Telephone/Fax	E-mail
Payment	Payment method (Please select the payment method by “√” ) 1. Advanced registration, payment by postal remittance 2. Advanced registration, payment by bank transferring 3. In site registration, payment by cash		
1. Registration fee of in-site registration will be paid at conference site on Dec.6-8 by cash. 2. Registration fee of advanced registration must be paid by Nov.25 by the way of remittance to the following bank account: <b>Beneficiary's name:</b> International Ecodesign and Microelectronic Packaging Research Institute Limited <b>Postal code:</b> 214028 <b>Unit address:</b> Room 301-304, Building A, No.21, Changjiang Road New District, Wuxi, Jiangsu Province P.R.China <b>Bank name:</b> Wuxi New District, Jiangsu Province, Agriculture Bank of China <b>Bank address:</b> No.58 Wang Zhuang Road, WND, Jiangsu, China <b>SWIFT:</b> ABOCCNBJ100 <b>Account number:</b> 1408010500141			

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           [temptm@mail.tsinghua.edu.cn](mailto:temptm@mail.tsinghua.edu.cn)  
           [xu.zhong@su.t.u-tokyo.ac.jp](mailto:xu.zhong@su.t.u-tokyo.ac.jp)

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## 2<sup>nd</sup> International Eco-Electronic Conference-Agenda

Thursday, Dec.7, 2006-2006 年 12 月 7 日

Chairman--- Jianzhong Huang, Ministry of Information Industry 主持:黄建忠, 信息产业部	
8:30-9:00	Opening speech 来宾致词
Chairman, Jusheng ma, Tsinghua University 主持:马莒生, 清华大学	
9:00-9:45	Introduction of Legislation of Chinese RoHS Jianzhong Huang, Ministry of Information Industry of China 电子信息产品污染控制管理办法立法情况介绍 黄建忠, 信息产业部
9:45-10:30	Introduction of Legislation of Chinese WEEE Liang Feng, State Development and Reforming Commission of China 中国 WEEE 现状和将来 冯良, 中国国家发展改革委员会 (待定)
10:30-10:45	Coffee break--茶歇
10:45-11:15	Tin Whisker Bridging Across Electrical Conductors Sony Mathew, Michael Osterman and Michael Pecht Center for Advanced Life Cycle Engineering (CALCE) University of Maryland
11:15-11:45	For a better global environment and trade – Harmonization aspects of requirements for electronics industry Hansjoerg Griese, Jutta Mueller, Lutz Stobbe Fraunhofer Institute for Reliability and Microintegration IZM
11:45-12:15	Introduction of Standardization of Chinese RoHS Weibing Xing, Electronic Standardization Research Institute of MII 电子信息产品污染控制标准化相关情况介绍 邢卫兵, 信息产业部电子工业标准化研究所
12:15-13:30	Lunch-午餐
Chairman--- Tadatomo Suga, University of Tokyo 主持:须贺唯知, 东京大学	
13:30-14:00	Development of New Lead Free System and Its Reliability Jusheng Ma, Tsinghua University 新型无铅系统研制及其可靠性 马莒生, 清华大学
14:00-14:30	A New Class of Thermal Interface Material based on Nano-Technology for Heat Removal in Electronics Packaging Johan Liu <sup>1,2</sup> , Michael Olugbenga Olorunyomi <sup>1</sup> , Xiuzhen Lu <sup>2</sup> , Wen Xuan Wang <sup>2</sup> , Tomas Aronsson <sup>1</sup> , Si Chen <sup>2</sup> and Dongkai Shangguan <sup>2</sup> <sup>1</sup> SMIT Center & Dept of Microtechnology and Nanoscience, University of

	Technology, Sweden <sup>2</sup> Key State Laboratory for New Displays and System Applications and SMIT Center, Shanghai University
14:30-15:00	Packaging and Green Technology on Led Sheng Liu, Huazhong University of Science and Technology 绿色照明的封装及技术讨论 刘胜, 华中科技大学
15:00-15:30	Challenge of RoHS on Chinese Electronic Industry By Chinese Industry people

15:30-16:00	Coffee Break-茶歇
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Panel discussion---Chinese RoHS and Its Global Impact Chair---Wayne Koh, USA 大会公开讨论---中国 RoHS 及其全球影响性 主持---Wayne Koh, 美国	
16:00-17:30	Jianzhong Huang, Ministry of Information Industry of China Weibing Xing, Electronic Standardization Research Institute of MII Dipl.-Ing. Hansjoerg Griese, IZM, Germany Other 2-3 members from Japan, USA 黄建中, 信息产业部 邢卫兵, 信息产业部电子工业标准化研究所 Dipl.-Ing. Hansjoerg Griese, IZM, Germany 日本、美国代表 2-3 名

18:00-20:00	Banquet
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**Friday, Dec.8, 2006-2006 年 12 月 8 日**

Session A Design & technology on lead-free & halogen-free system 分会 A 无铅、无卤系统的设计和技术	
8:10-8:30	The Mutual Impact of Lead-Free Soldering and Fluxing Technology Ning-Cheng Lee, Indium Corporation of American
8:30-8:50	Environmentally Friendly Electronics Packaging Materials Itsuo Watanabe, Hitachi Chemical Co., Ltd.
8:50-9:10	Implementing RoHS and Green Policy in an International Power Management Manufacturing Service Provider Operating in China Teng Hui, Yang Hongbo, Zhou Ming, Anthony C. Tsui Advanced Engineering Department, GEM Electronics (Shanghai) Co., Ltd
9:10-9:30	Green Sensor application of thin film Hall sensors Dr. Ichiro Shibasaki, Dr. Shuichiro Ogawa New Business Development, Asahi Kasei Corporation
9:30-9:50	IC Green Packaging---Foundation of Green Electronics Hongjun Yan, Nantong Fujitsu Microelectronics Co., Ltd.



	绿色电子的基础—集成电路绿色封装 严宏军,南通富士通微电子
9:50-10:10	Coffee break-茶歇
10:10-10:30	Research Report on Lead Free Solder of SnCuNiCe Mingbin Su, Kunshan Chengli Soldering Co. Ltd. 有关无铅焊料 SnCuNiCe 的研究报告 苏明斌, 昆山成利焊锡制造有限公司
10:30-10:50	Halogen Free Cables and Wires for Our Green Life Eddie Li, Jay Luo and Hugo Leung, LTK Wiring Company
10:50-11:10	Fine Lead-free solder paste for high density Packaging and its key-preparation Hu-qiang, Xu-jun, Zhang fu-wen General Research Institute for Non-ferrous Metals 高密度组装用精细无铅焊膏相关材料及其关键制备技术 胡强, 徐骏, 张富文 北京有色金属研究总院复合材料中心, 北京康普锡威焊料有限公司
11:10-11:30	Critical Parameters in Voiding Control at Reflow Soldering Ning-Cheng Lee Indium Corporation of American
11:30-11:50	Novel SACX solders with superior drop test performance Weiping Liu and Ning-Cheng Lee Indium Corporation of American

12:00-13:00	Lunch-午餐
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Session B—Eco-Design, management, supply chain and global collaboration 分会 B—绿色设计, 管理, 供应链和全球合作	
13:00-13:20	Europe - China Cooperation in Green Electronics Production Research (EC-GEPRO) Otto Andersen <sup>1</sup> , Idun Husabø Anderssen <sup>1</sup> , Johan Liu <sup>2</sup> , Teng Wang <sup>2</sup> , David Whalley <sup>3</sup> , Helge Kristiansen <sup>4</sup> , Tom Ove Grønlund <sup>4</sup> , Krystyna Bukat <sup>5</sup> , Xiuzhen Lu <sup>6</sup> , Zhaonian Cheng <sup>6</sup> <sup>1</sup> Western Norway Research Institute <sup>1</sup> , <sup>2</sup> Chalmers Technical University, Sweden, <sup>3</sup> Loughborough University, UK, <sup>4</sup> Conpart AS, Norway, <sup>5</sup> ITR - Tele and Radio Research Institute, Warsaw, Poland, <sup>6</sup> Sino Swedish Microsystem Integration Technology Center, Shanghai University
13:20-13:40	Importance and necessity on the Ecodesign of Chinese household home appliance Household Zhongfan Zhou, Chinese Research Academy of Environmental Science 中国家用电器产品进行绿色设计的必要性和紧迫性 周仲凡, 中国环境科学研究院
13:40-14:00	Eco-design potentiality of Flexible Printed Circuit (FPC) for electronic equipment Hidetaka Hayashi, The University of Tokyo

14:00-14:20	Green manufacturing-- sustainable development strategy Weixiang Guo & Jingxing Jiang, China Telecommunication Technology Labs 绿色制造—可持续发展新战略 郭伟祥, 蒋京鑫, 信息产业部电信研究院中国泰尔实验室
14:20-14:40	Extended Producer Responsibility: An examination of its impact on innovation and greening products Chris van Rossem, Naoko Tojo, Thomas Lindqvist

14:40-15:00	Coffee Break-茶歇
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Session C: RoHS Standard, Testing Technology and Equipment 分会 C: RoHS 标准, 测试和设备	
15:00-15:20	Study on minimal size of component unnecessary to further disjoint in RoHS Testing Luo Daojun and Bian Zhengyun China Ceprei Lab., Guangzhou, P.R.China
15:20-15:40	Environmental Regulations and Compliance Standardization of Requirements Michael Kluwin, Juniper Networks, Inc.
15:40-16:00	A quick green certified test by X-ray fluorescence spectrometry for RoHS compliance L. Hua <sup>1,2</sup> , Y. C. Chan <sup>1*</sup> , Y.P.Wu <sup>2</sup> , B. An <sup>2</sup> , A. Sharif <sup>1</sup> 1*. Department of Electronic Engineering, City University of Hong Kong 2. Huazhong University of Science & Technology, Wuhan, China
16:00-16:20	Application of X-Ray Spectrometer on RoHS Measurement Dr. Zhaogui Liu, Skyray Instrument LTD. 论 X 荧光光谱仪在 RoHS 检测中的应用 刘召贵博士, 深圳天瑞仪器有限责任公司董事长
16:20-16:40	Scheme Consideration of X-Ray Spectrometer for EU RoHS & WEEE Bandwise Technology Development Co., Ltd. 针对欧盟 ROHS & WEEE 指令用于有害元素检测和控制的 X 荧光分析仪综合选型方案 北京邦鑫伟业技术开发有限公司

Session D—Electronic and electrical sets recycle activity, technology and management. 分会 D—电子回收产业、技术和管理	
16:40-17:00	A Comparative Study of Recycling Strategies for E-waste in Japan and Korea Chung Sung Woo, Graduate School of Economics and Business Administration, Hokkaido University Prof. Yoshida Fumikazu, Graduate School of Public Policy, Hokkaido University
17:00-17:20	Research on Chinese E-Waste recycle System. Jiping Yang, Dong Xiang, Peng Mou, Guanghong Duan Tsinghua University 中国废旧电子电器产品回收处理体系建设研究 杨继平 <sup>[1]</sup> 向东 <sup>[1]</sup> 牟鹏 <sup>[1]</sup> 段广洪 <sup>[1]</sup> 尉黎 <sup>[2]</sup> <sup>[1]</sup> 清华大学精密仪器与机械学系 <sup>[2]</sup> 轻工业环境保护研究所

17:20-17:40	Research on cycle manufacturing of Chinese electronic and electrical sets in China Youliang Zhang, Chinese Household Home Appliance Research Institute 中国电子电器产业循环制造机制探讨 张友良, 中国家电研究院
17:40-18:00	EEE pollution –Introduction of global environment regulations Yunfei Xu, Muzhen Ke, SGS 徐云飞, 柯木珍, SGS 通标标准技术服务有限公司
18:30-20:00	Dinner-晚宴

**Saturday, Dec.9, 2006**

Industry tour

2006年12月9日

参观